

Title (en)
SEMICONDUCTOR COMPONENT COMPRISING A SENSOR SURFACE OR AN ACTUATOR SURFACE, AND METHOD FOR PRODUCING THE SAME

Title (de)
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Title (fr)
COMPOSANT SEMI-CONDUCTEUR PRESENTANT UNE SURFACE DE CAPTEUR OU D'ACTIONNEUR ET PROCEDE POUR LE PRODUIRE

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Abstract (en)
[origin: WO03067657A2] The invention relates to an electronic semiconductor component comprising a semiconductor chip (4) having an active chip surface (47) which is bordered by a raised metal frame (45). A plastic housing (10) comprises a recess (63; 102) for the active chip surface (47) within the metal frame (45), leaving said chip surface free. The invention also relates to a method for producing the inventive electronic semiconductor component.

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